



SMTA International Booth 424
September 17 - 21, 2017
Donald E. Stephens Convention Center,
Rosemont, IL, USA

YOU ARE INVITED!

SPI → AOI → AXI



TR7007QI 3D SPI

- Multi-angle 2D + 3D Coverage
- 2015 Global Tech Award Winner
- Market Leading Inspection Speed and Precision
- Fast **CoaXPress** Imaging



TR7500QE 3D AOI

- Multi-angle 2D + 3D Coverage
- 4-way DLP Fringe Projection
- **3D Solder Joint Inspection**
- Fast **CoaXPress** Imaging



TR7600 SIII 3D AXI

- Ultra-high Speed Inline 3D X-ray Inspection
- **Planar CT** for True 3D Solder Review

Industry Solution **4.0**

Visit TRI at SMTA International Electronics Exhibition 2017!

Visit us at booth **424** for a personal demo of our Complete 3D Solution: SPI, AOI, AXI and ICT solutions working with Industry 4.0 management to improve yields and reduce production costs.



Join the **SMTAI TECH TOUR** to discover the ultimate solder joint inspection for improving production yields!

To book a personal demonstration during SMTAI 2017, please contact triusa@tri.com.tw or call 408-567-9898